

Electronic Patent Application Fee Transmittal**Application Number:**

10825839

Filing Date:

15-Apr-2004

Title of Invention:

Semiconductor Packages Comprising Interposer Constructions

First Named Inventor/Applicant Name:

Lee Teck Kheng

Filer:

Donald B. Kenady/Lorie Smith

Attorney Docket Number:

MI22-2460

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees**Description****Fee Code****Quantity****Amount****Sub-Total in
USD(\$)****Basic Filing:****Pages:****Claims:****Miscellaneous-Filing:****Petition:****Patent-Appeals-and-Interference:****Post-Allowance-and-Post-Issuance:****Extension-of-Time:**

Extension - 1 month with \$0 paid

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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				310